DATASHEET

ELCH08-5070J6J7283910-N1B

Received
□ MASS PRODUCTION
■ PRELIMINARY
□ CUSTOMER DESIGN
DEVICE NO. : DHE-0002381
PAGE : 12

Revised record		
REV.	DESCRIPTION	RELEASE DATE
1	New spec	2014.02.18

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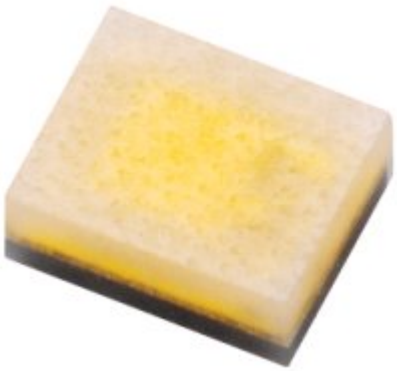


Features

- Feature of the device：small package with high efficiency
- Typical luminous flux@ 1A：250 lm
- Optical efficiency@1A：82.5 lm/W
- ESD protection (according to JEDEC 3b) (HBM air or contact discharge)up to 8KV
- Binning Parameters：Brightness, Forward Voltage and Chromaticity
- Grouping parameter: total luminous flux, color coordinates.
- RoHS compliant & Pb free.

Applications

- Mobile Phone Camera Flash(Camera flash light /strobe light for mobile devices)
- Torch light for DV(Digital Video) application
- Indoor lighting applications
- Signal and symbol luminaries for orientation maker lights (e.g. steps, exit ways, etc.)
- TFT backlighting
- Exterior and interior illumination applications
- Decorative and Entertainment Lighting
- Exterior and interior automotive illumination

Device Selection Guide

Chip Materials	Emitted Color
InGaN	White

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
DC Forward Current (Torch Mode)	I_F	350	mA
Peak Pulse Current	I_{Pulse}	1500	mA
ESD Resistance (JEDEC 3b)	V_B	8000	V
Reverse Voltage	V_R	Note 1	V
Junction Temperature	TJ	145	°C
Operating Temperature	T_{Opr}	-40 ~ +85	°C
Storage Temperature	T_{Stg}	-40 ~ +100	°C
Soldering Temperature	T_{Sol}	260	°C
Allowable Reflow Cycles	n/a	2	Cycles
Substrate Temperature	T_s	70(IF=1000mA)	°C
Viewing Angle$_{(2)}$	$2\theta_{1/2}$	120	Deg
Power Dissipation (Pulse Mode)	P_d	6.42	W

Notes:

1. The CHIN series LEDs are not designed for reverse bias used.
2. View angle measurement tolerance±5°
3. Avoid operating CHIN series LEDs at maximum operating temperature exceed 1 hour.
4. All specification are assured by reliability test for 1000hr, IV degradation less than 30%.
5. All reliability items are tested under good thermal management with 1.0x 1.0 cm^2 MCPCB.

Electro-Optical Characteristics (Ts=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Flux(1)	Iv	200	250	----	lm	I_F=1000mA
Forward Voltage(2)(3)	V_F	2.85	----	3.95	V	
Color Temperature	CCT	5000	----	7000	K	

Forward Voltage Binning

Bin	Symbol	Min.	Typ.	Max.	Unit	Condition
2832	V_F	2.85	----	3.25	V	I_F=1000mA
3235	V_F	3.25	----	3.55		
3539	V_F	3.55	----	3.95		

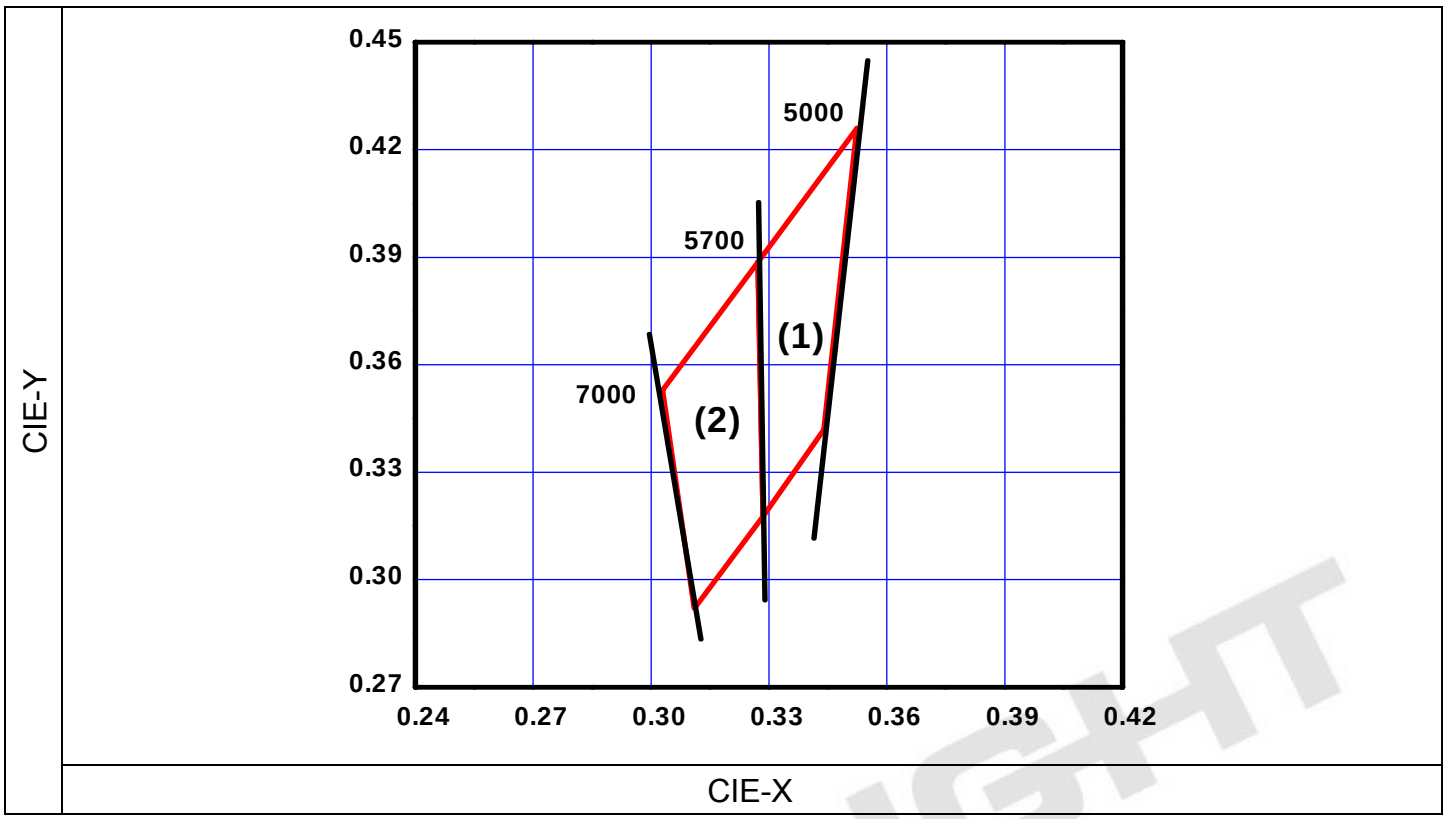
Luminous Flux Binning

Bin	Symbol	Min.	Typ.	Max.	Unit	Condition
J6	Iv	200	----	250	lm	I_F=1000mA
J7	Iv	250	----	300		

Notes:

1. Luminous Flux, illuminance measurement tolerance：±10%
2. Forward voltage measurement tolerance：±0.1V
3. Electric and optical data is tested at 50 ms pulse condition.
4. Forward voltage is higher than 2V at 1mA
5. Temperature of solder pad：25°C2

White Bin Structure



Notes：
1.Color Bin (1) :5057K
2.Color Bin (2) :5770K

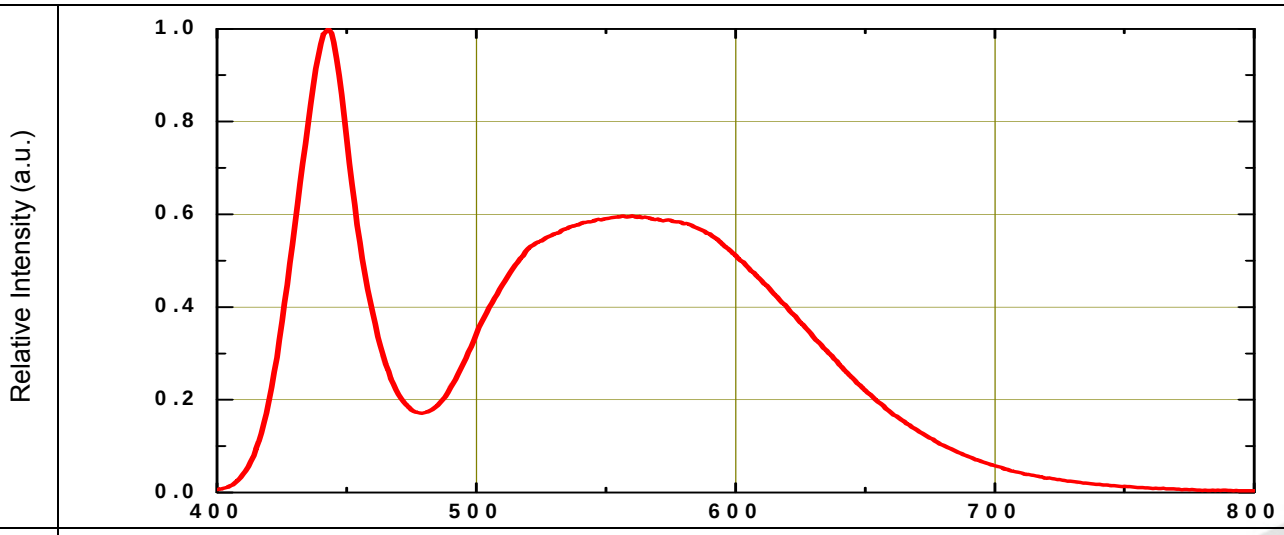
Bin	CIE-X	CIE-Y	Reference Range
5057	0.3272	0.3888	5000K ~ 5700K
	0.3524	0.4261	
	0.3440	0.3420	
	0.3285	0.3178	
5770	0.3000	0.3486	5700K ~ 7000K
	0.3272	0.3888	
	0.3285	0.3178	
	0.3110	0.2920	

Notes:

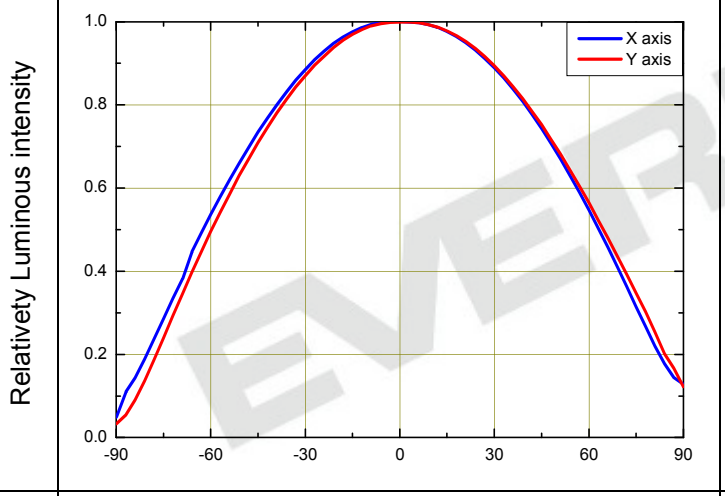
1. Color coordinates measurement allowance：±0.01
2. Color bins are defined at I_F=1000mA operation.

Typical Electro-Optical Characteristics Curves

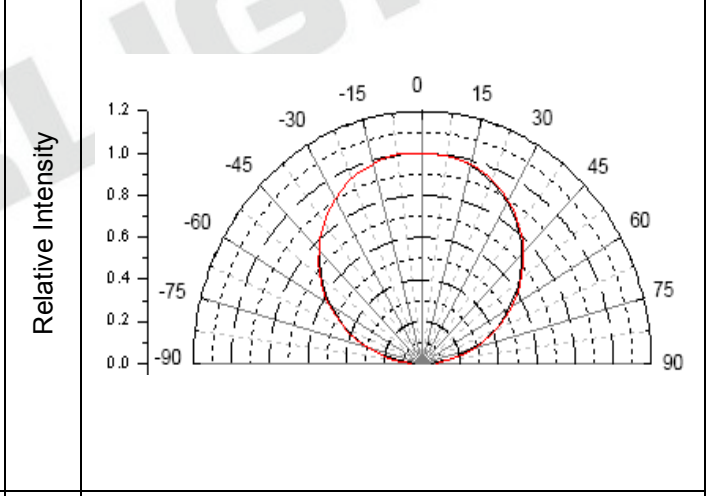
Relative Spectral Distribution , I_F=1000mA @ 50ms, $T_{solder\ pad}$=25℃



Typical Radiation Patterns



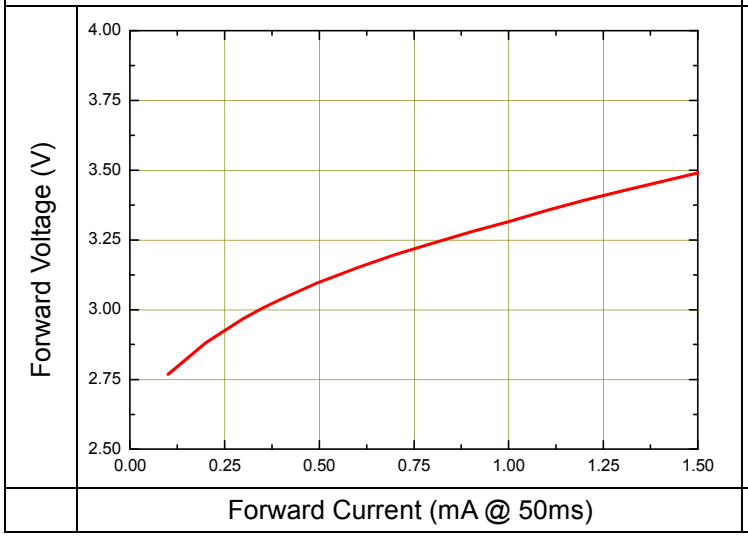
Typical Polar Radiation Pattern for Lambertian



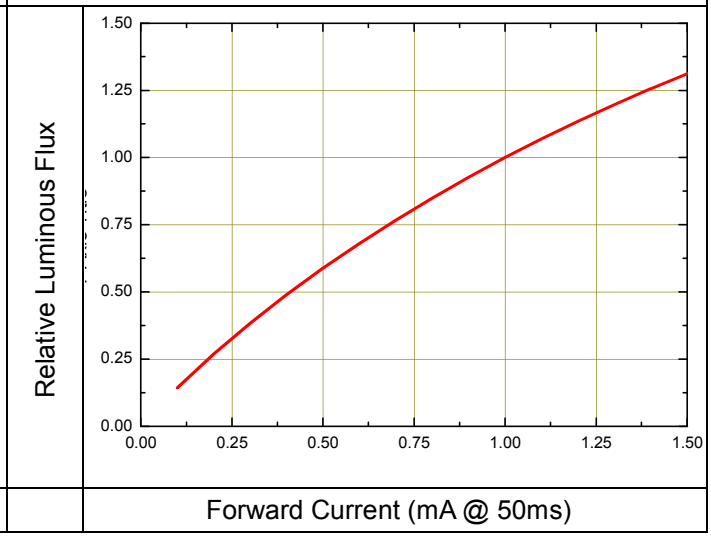
Notes:

1. $2\theta_{1/2}$ is the off axis from lamp centerline where the luminous intensity is 1/2 of the peak value.
2. View angle tolerance is ± 5°

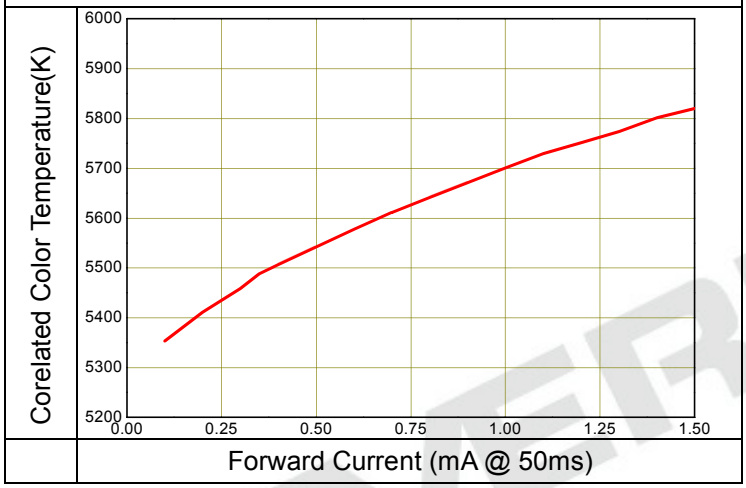
Forward Voltage vs. Forward Current ($T_{solder\ pad}$=25°C)



Relative Luminous Flux vs. Forward Current ($T_{solder\ pad}$=25 °C)



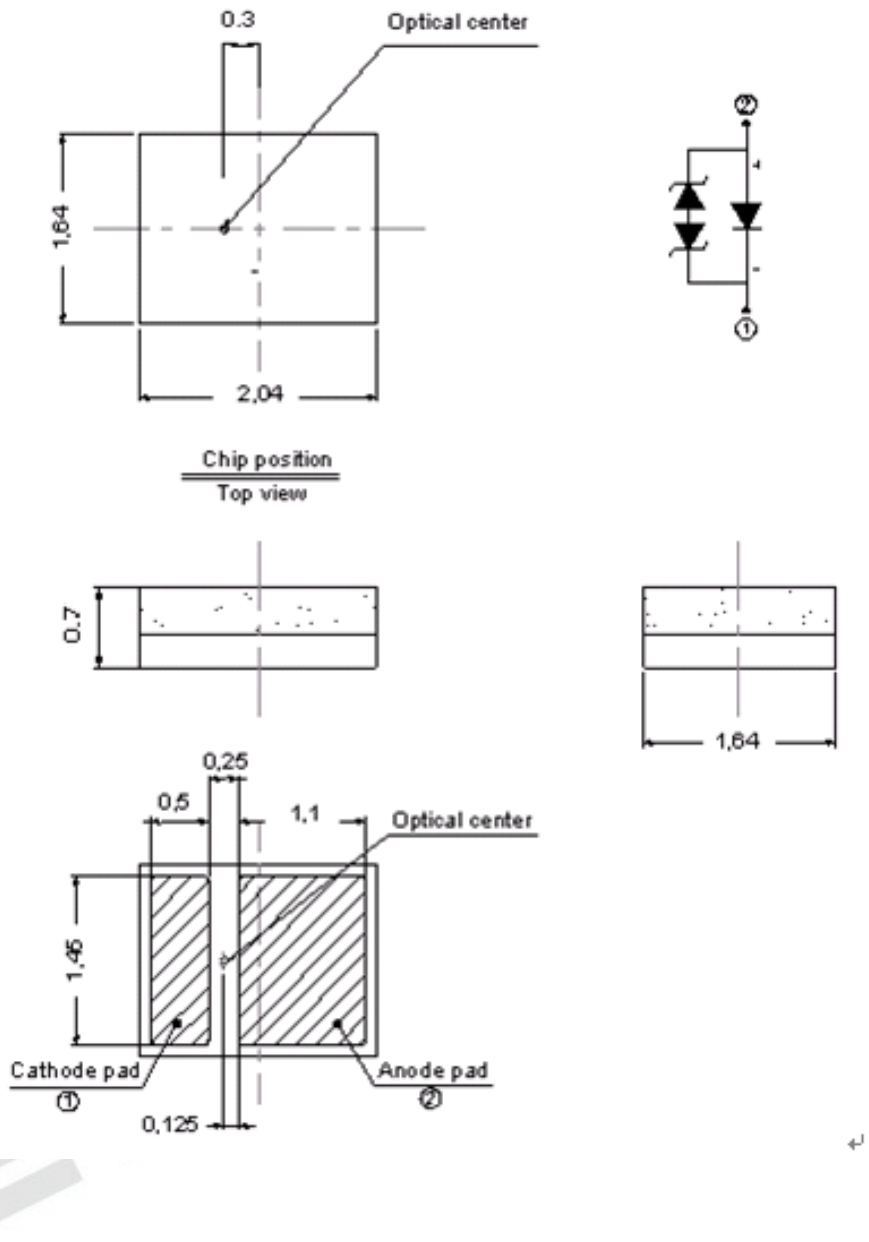
CCT vs. Forward Current ($T_{soldering\ pad}$=25°C)



Notes:

1. All correlation data is tested under superior thermal management with 1 x 1 cm^2 MCPCB.

Package Dimension



Notes:

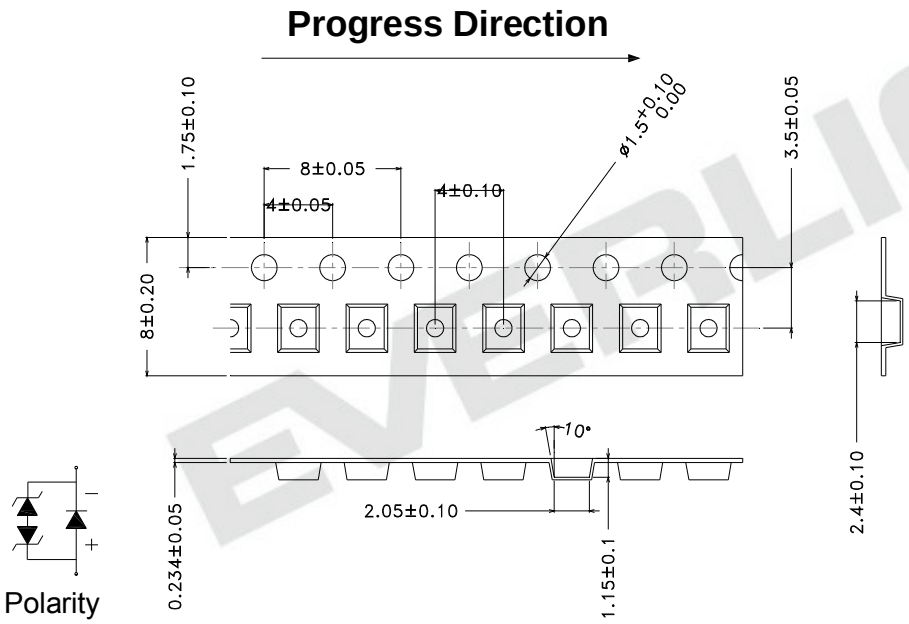
1. Dimensions are in millimeters.
2. Tolerances unless mentioned are ± 0.1mm.

Moisture Resistant Packing Materials

Product Labeling

- CPN：Customer's Product Number
- P/N：Everlight Product Number
- QTY：Packing Quantity
- CAT：Luminous Flux (Brightness) Bin
- HUE：Color Bin
- REF：Forward Voltage Bin
- LOT No：Lot Number

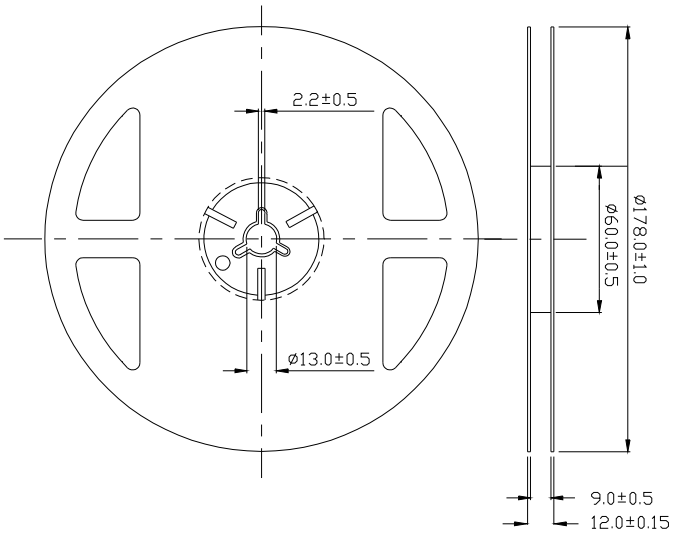
Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Notes:

1. Dimensions are in millimeters.
2. Tolerances for fixed dimensions are ±0.1mm.

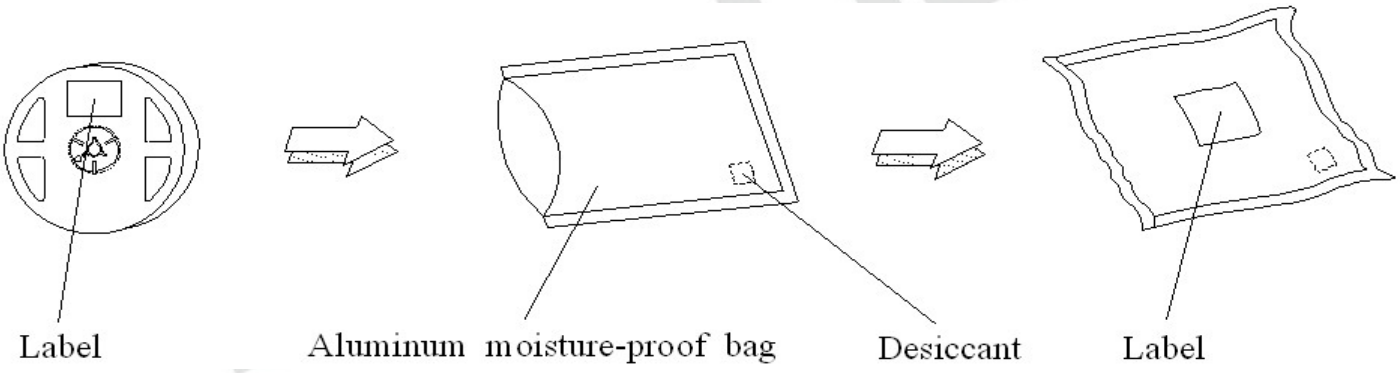
Emitter Reel Dimensions



Notes:

1. Dimensions are in millimeters.
2. Tolerances unless mentioned are ±0.1mm.

Moisture Resistant Packing Process



Notes:

Reflow Soldering Characteristics

Soldering and Handling

1. Over-current-proof

Though CHIN series has conducted ESD protection mechanism, customers must not use the device in reverse and should apply resistors for extra protection. Otherwise, slight voltage shift may cause enormous current shift and burn out failure would happen.

2. Storage

2.1 Do not open the moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be stored at temperature less than 30°C and relative humidity less than 90%

2.3 After opening the package, the LEDs should be stored at temperature less than 30°C and relative humidity less than 85%.

1.4 If the moisture absorbent material (silicone gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be implemented based on the following conditions: Pre-curing at 60±5°C for 24 hours.

3. Thermal Management

3.1 For maintaining the high flux output and achieving reliability, CHIN series LEDs should be mounted on a metal

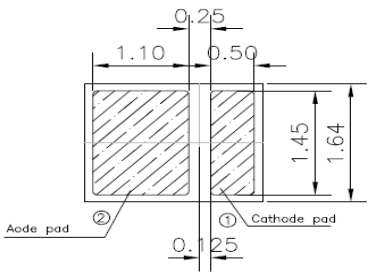
core printed circuit board (MCPCB), with proper thermal connection to dissipate approximately 1W to 5W of thermal energy under normal operation.

3.2 Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and LEDs lifetime will decrease critically.

3.3 When operating , the solder pad temperature (or the board temperature nearby the LED) must controlled under 70°C.

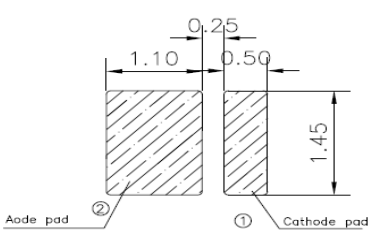
4. Soldering Condition

4.1 Soldering Pad



Bot.view

Component bottom view

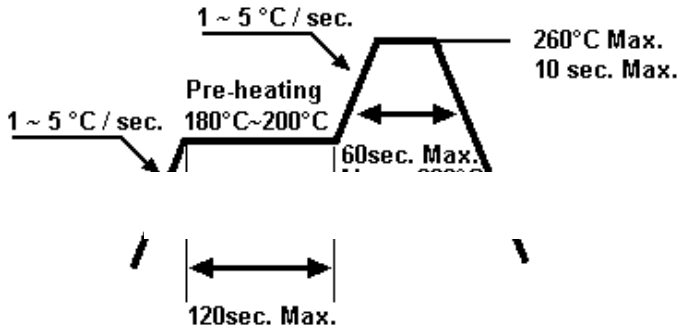


Soldering patterns

Recommended soldering pattern layout

4.2 For Reflow Process

4.2.1 Lead reflow soldering temperature profile



4.2.2 Reflow soldering should not be done more than two times.

4.2.3 While soldering, do not put stress on the LEDs during heating.

4.2.4 After soldering, do not warp the circuit board.